

1752-2 1.1

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Declaration Class*

Form Type* Distribute Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

	Infoliation						
Supplier Information							
Company Name *	Company Unique ID	Unique ID Authority	Response Date*				
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Feb 22, 2014 03:32 AM				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *				
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com				
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *				
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com				
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Requester Item Number Mfr Item Number		Mfr Item Name		Effective Date	Version	N	fanufacturing Site	utfacturing Site Weight*		Unit Type	
LM339N	LM	1339N	DIP-14				SUBCONTRACTOR		1.042694	g	Each
Manufacturing Process Information											
Terminal Finish	Base Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		No Reflow cycles			
Matte Tin (Sn)	CU Alloy	Not Applicable			С		seconds		Not A	Not Applicable	

* Required Field

RoHS Material	Composition Declaration	Declaration Type * Custom					
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium						
restriction of the	Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the cou ise of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this docun irchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.						
ensure our production independently vertices	The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.						
Safety Data Sheet miniscule quantit	the content disclosed herewith is approximate and is based on various methods including, engineering calculations, is, analytical measurements. Fairchild may update this document without notification. This statement may not include of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed contain alternate substances of similar composition.	le information regarding the					
RoHS Declaration	* 1 - Item(s) does not contain RoHS restricted substances per the definition above Sup	plier Acceptance * Accepted					
1 · · · · · · · · · · · · · · · · · · ·	ne declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exer ponse in the RoHS Declaration above and choose all applicable exemptions.	nptions, then select the					
Exemption None	List Version EL-2011/534/EU						
Declaration Sign	ature						

David Loncosto

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DIP-14

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.905	Supplier		Silicon	0.905	7440-21-3	868
Die Attach	Other Organic Materials	0.098	Supplier		Acrylic Resin	0.025	54208-63-8	23
			Supplier		Silver	0.074	7440-22-4	71
Encapsulation	Thermoplastics	691.070	В	Antimony/Antimony Compounds	Antimony Trioxide	20.700	1309-64-4	19852
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	6.910	6386-73-8	6627
			Supplier		Carbon Black	3.460	1333-86-4	3318
			Supplier		Epoxy Resin	197.000	29690-82-2	188934
			Supplier		Silica, vitreous	463.000	60676-86-0	444042
Lead Frame	Copper & its alloys	327.672	Supplier		Copper	318.000	7440-50-8	304979
			Supplier		Iron	7.540	7439-89-6	7231
			Supplier		Phosphorus	0.098	7723-14-0	94
			Supplier		Silver	1.640	7440-22-4	1573
			Supplier		Zinc	0.394	7440-66-6	378
Plating	Other Nonferrous metals & alloys	22.600	Supplier		Tin	22.600	7440-31-5	21675
Wire Bond	Precious metals	0.348	Supplier		Gold	0.348	7440-57-5	334